

Dimens Chip Siz

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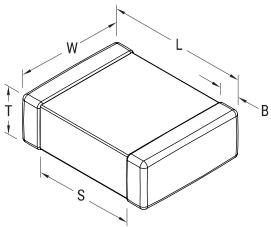
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C1210X331G2TACTU

Aliases (C1210X331G2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 330 pF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



Click here for the 3D model.		Marking
		AEC-Q200
		Typical Component W
	Shelf Life	
		MSL
sions		Specifications
ize	1210	Capacitance
	3.3mm +/-0.4mm	Measurement Conditi

0.78mm +/-0.20mm

0.6mm +/-0.25mm

1.5mm MIN

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	330 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	2%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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